

Excellent Integrated System Limited

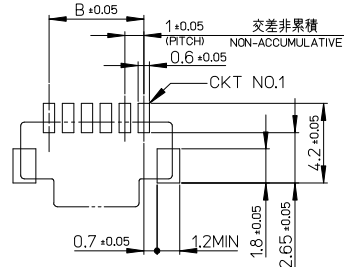
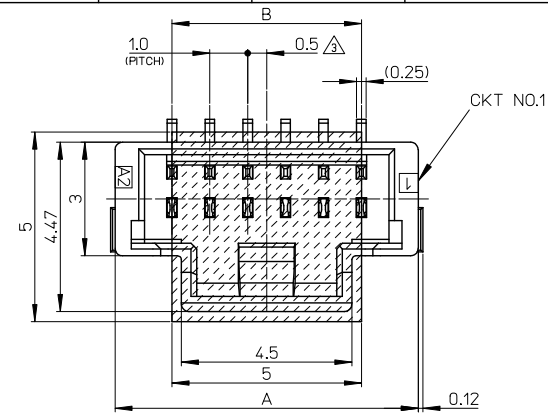
Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[501331-0807](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF)
SCALE:5:1

番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON UL94V-0, COLOR:SEE TABLE
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

※対応可能な極数は、別途お問い合わせ下さい。

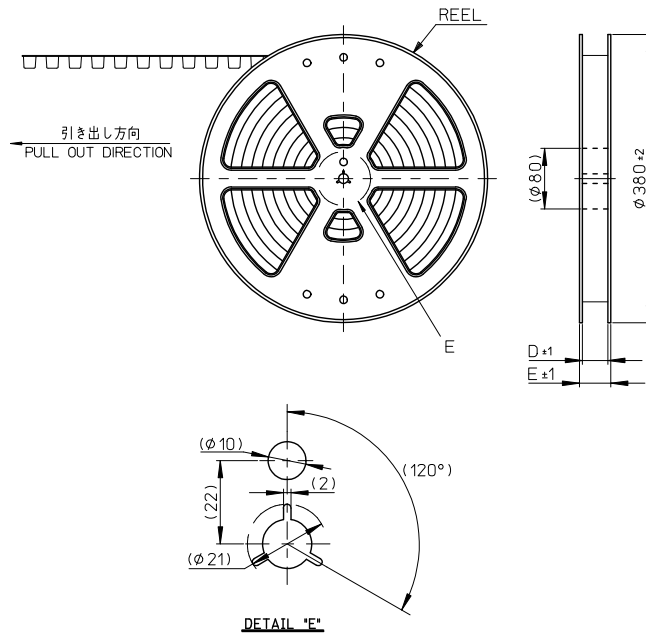
14.0	17.0	501331-1507	15	501331-***07
13.0	16.0	501331-1407	14	
12.0	15.0	501331-1307	13	
11.0	14.0	501331-1207	12	
10.0	13.0	501331-1107	11	
9.0	12.0	501331-1007	10	
8.0	11.0	501331-0907	9	
7.0	10.0	501331-0807	8	
6.0	9.0	501331-0707	7	501331-0607
5.0	8.0	501331-0607	6	
B	A	MATERIAL NO.	CKT.	MODEL NO.

NOTES.

1. 嵌合相手: 501330-****
MATE WITH: 501330-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 2~5極は、SD-501331-001を参照下さい。
REFER TO SD-501331-001 ABOUT 2-5CKT.
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

REVISED	EC NO. J2014-1509 DRWN:YAJIMA01 CHKD:KASAKAWA APPR:MIKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
					MM ONLY		10:1		METRIC			
			10 UNDER	±0.2	DRAWN BY	DATE	TITLE		1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT			
			10 OVER 30 UNDER	±0.25	CHECKED BY	DATE						
			30 OVER	±0.3	APPROVED BY	DATE						
			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501331-002		1 OF 2			
					SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
					A3							

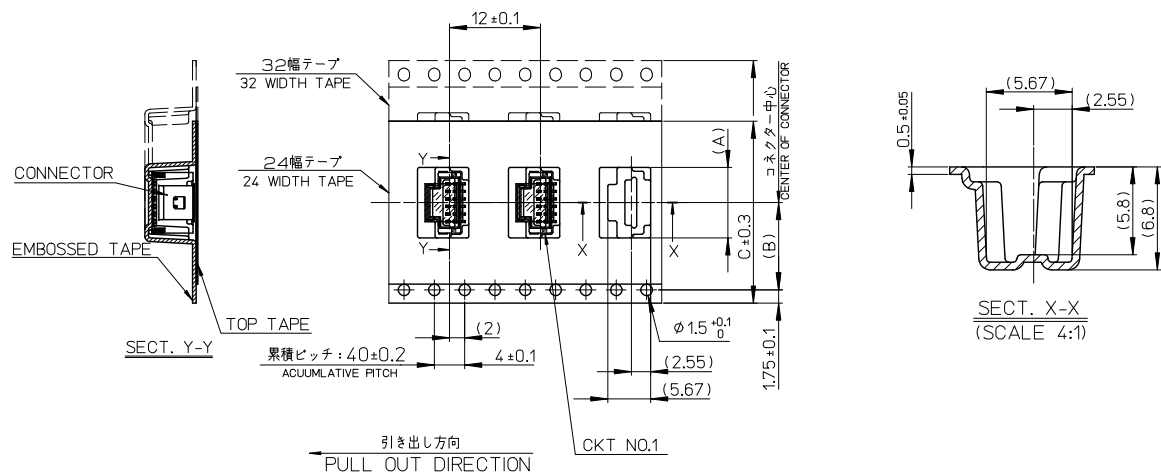
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Rev G 2012/01/25



NOTES.

- 製品詳細寸法については製品単体図面を参照ください。
ABOUT DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 1100個/リール
NUMBER OF CONNECTORS: 1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH
トップテープ接着部 (空エンボス)
20 PIECES. MIN.
TOP TAPE BONDED PART (EMPTY)
部品挿入部
COMPONENT
SUPPLIER
末端部
(空部)
TAIL PART
(EMPTY)
40MIN.
- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET・PE・REF
TOP TAPE
リール: ポリスチレン (リサイクル材を含む)
REEL: POLYSTYRENE (RECYCLE MATERIAL CONTAINED)
- ELV 及び RoHS適合品
ELV AND ROHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501331-**-07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501331-**-07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501331-001参照)
REFER TO PS-501331-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED	EC NO. J2014-1509	2014/04/04	TIDRWN:TAJIMA01	2014/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	1.0 WIRE TO BOARD CONN. WAfer ASS'Y (1-ROW S/T) EMBSTP PKG molex		
	CHKD:KASAKAWA	2014/04/07	APPR:MIKITA	10 UNDER		±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE						
				10 OVER 30 UNDER		±0.25	CHECKED BY MYAGI	DATE 2005/01/18							
				30 OVER		±0.3	APPROVED BY ANODA	DATE 2005/01/18							
	ANGULAR	±1 °	MATERIAL NO.			DOCUMENT NO.		SHEET NO. 1 OF 3							
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3			SD-501331-004									
	REV					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



37.4	33.4	32	14.2	18.3	5013311507
				17.3	5013311407
				16.3	5013311307
				15.3	5013311207
				14.3	5013311107
				13.3	5013311007
29.4	25.4	24	11.5	12.3	5013310907
				11.3	5013310807
				10.3	5013310707
				9.3	5013310607
E	D	C	(B)	(A)	製品番号 MATERIAL NO.

REVISED		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
EC NO. J2014-1509		DRAWN BY		DATE		---		METRIC		◎	
TIDRWN:YAJI MA01		10 UNDER		±0.2		NYOSHIDA		2005/01/18		TITLE	
CHKD:KASAKAWA		10 OVER 30 UNDER		±0.25		CHECKED BY		DATE		1.0 WIRE TO BOARD CONN.	
APPR:MIKITA		30 OVER		±0.3		MYAGI		2005/01/18		WAFER ASS'Y (1-ROW S/T)	
REV		ANGULAR		±1 °		APPROVED BY		DATE		EMBSTP PKG	
		DRAFT WHERE APPLICABLE		MUST REMAIN		ANODA		2005/01/18		molex	
		WITHIN DIMENSIONS				MATERIAL NO.		DOCUMENT NO.		SD-501331-004	
						SEE SHEET 3				SHEET NO.	
						SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX		2 OF 3	
						A3		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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